

Application Number: 10/654,167

Dkt No.: DT-024-US-01

Listing of Claims

1.(Previously presented) A hot melt adhesive composition comprising:
(a) an ethylene methyl methacrylate copolymer having a peak melting point of no greater than about 67°C ± 6°C;
(b) a wax; and
(c) a tackifying resin,
with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate.

2.(Original) The composition of claim 1 further comprising an oil.

3.(Cancelled)

4.(Previously presented) The composition of claim 1 further comprising an antioxidant.

5.(Previously presented) The composition of claim 1 further comprising a copolymer.

6.(Previously presented) The composition of claim 1 further comprising a block copolymer.

7-8.(Cancelled)

9.(Original) A package formulation comprising:

- (a) the composition of claim 1; and
- (b) instructions for application of the composition to a substrate.

10.(canceled)

Application Number: 10/654,167

Dkt. No.: DT-024-US-01

11.(Previously presented) A hot melt adhesive composition consisting essentially of:

- (a) an autoclave reactor ethylene methyl methacrylate copolymer;
- (b) a wax; and
- (c) a tackifying resin.

12.(Original) The composition of claim 11 further consisting essentially of an oil.

13.(Cancelled)

14.(Previously presented) The composition of claim 11 further consisting essentially of an antioxidant.

15-16.(canceled)

17.(Original) The composition of claim 11 further consisting essentially of a block copolymer.

18.(canceled)

19.(Withdrawn) A method of using a hot melt adhesive composition comprising:

- (a) providing a hot melt adhesive composition comprising:
 - (i) an ethylene methyl methacrylate copolymer having a peak melting point of no greater than about $67^{\circ}\text{C} \pm 6^{\circ}\text{C}$; and
 - (ii) a tackifying resin,
- with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate; and
- (b) applying the composition to a substrate.

20.(Withdrawn) The method of claim 19 wherein the method is a method of using the hot melt adhesive for book binding.

06/29/06 10:51 FAX 6512365128

HB FULLER PATENTSTY

005

Application Number: 10/654,167

Dkt. No.: DT-024-US-01

21-25. (Canceled)